



Version 4 ColdFire Core Announcement

October, 1998



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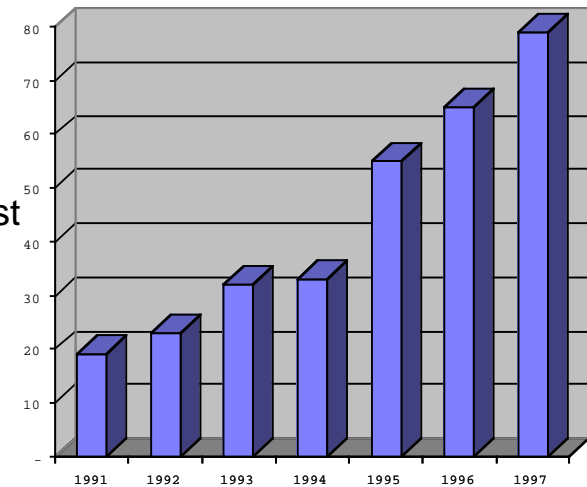
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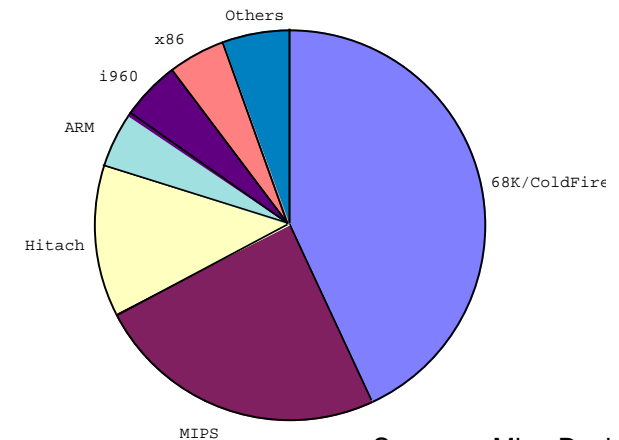
ColdFire® Is...

- An Instruction Set
 - **ColdFire** is 68K
 - Binary compatible with MicroAPL emulator and translator
 - 68K/ColdFire is most widely used 32-bit embedded architecture
 - Desktop-specific functions eliminated to minimize complexity/cost
 - SW supported functions: BCD, Rotate, etc.
 - Simplified exception model
- An Implementation Methodology Designed for Reuse
 - All **ColdFire** cores are 100% fully synthesizable
 - Parameterizable - all options exist within a single design description
 - Configurable
 - Generic local-memory controllers support a range of sizes
 - Choose size using compiled memory arrays
 - Hierarchical architecture
 - Multiple buses provide layers of bandwidth + modularity
 - Standard internal bus structure provides simple interface
 - Design-for-Test
 - Muxed D-FF rising-edge clocked design
 - ATPG scan vectors for stuck-at, speed testing
 - BIST test methodology for memories
 - Deployment focused on soft macro RTL + support of hard macros

68K/ColdFire Millions of Units Shipped



1997 Market Share



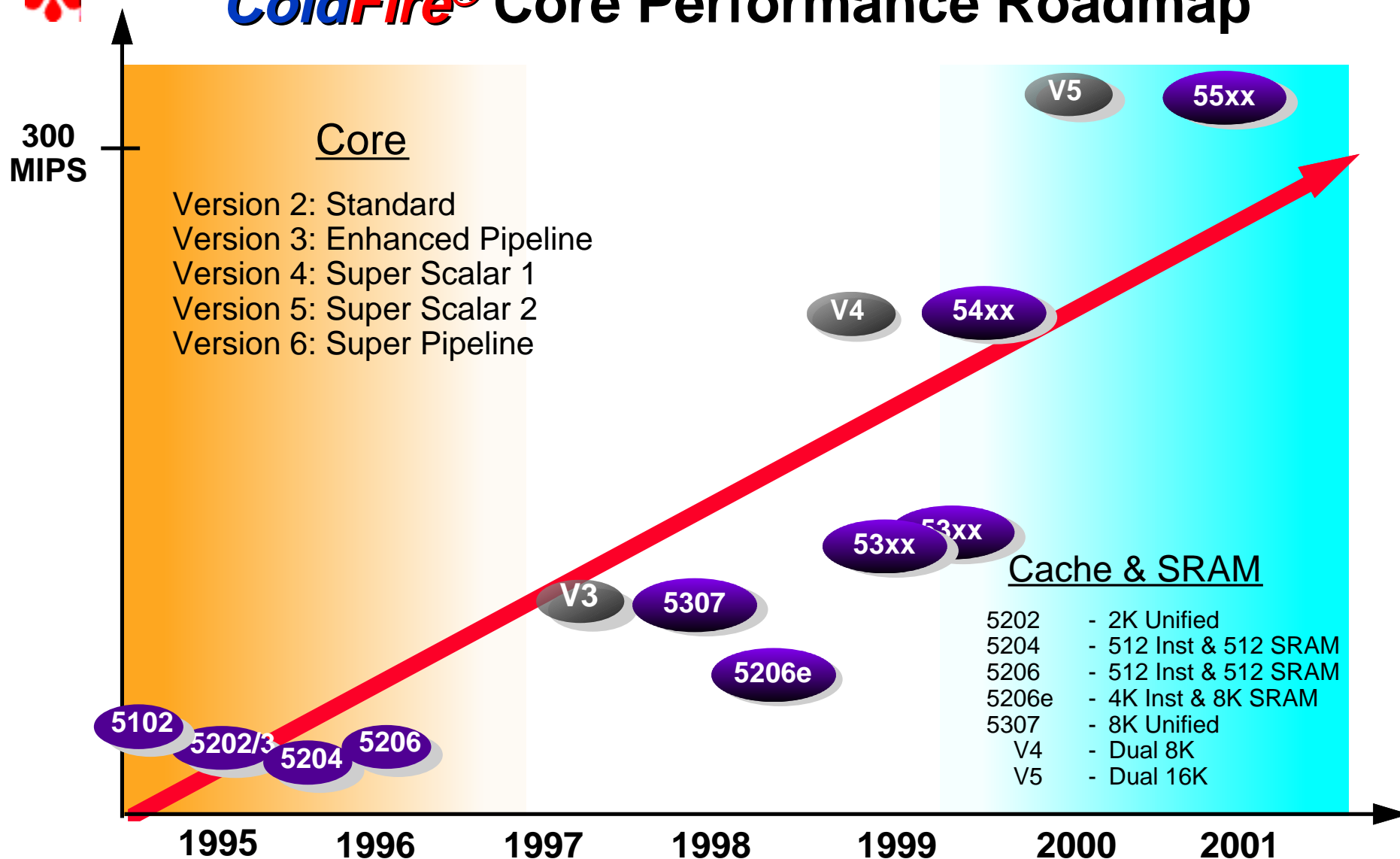
Sources: MicroDesign Resources, Motorola



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ColdFire® Core Performance Roadmap



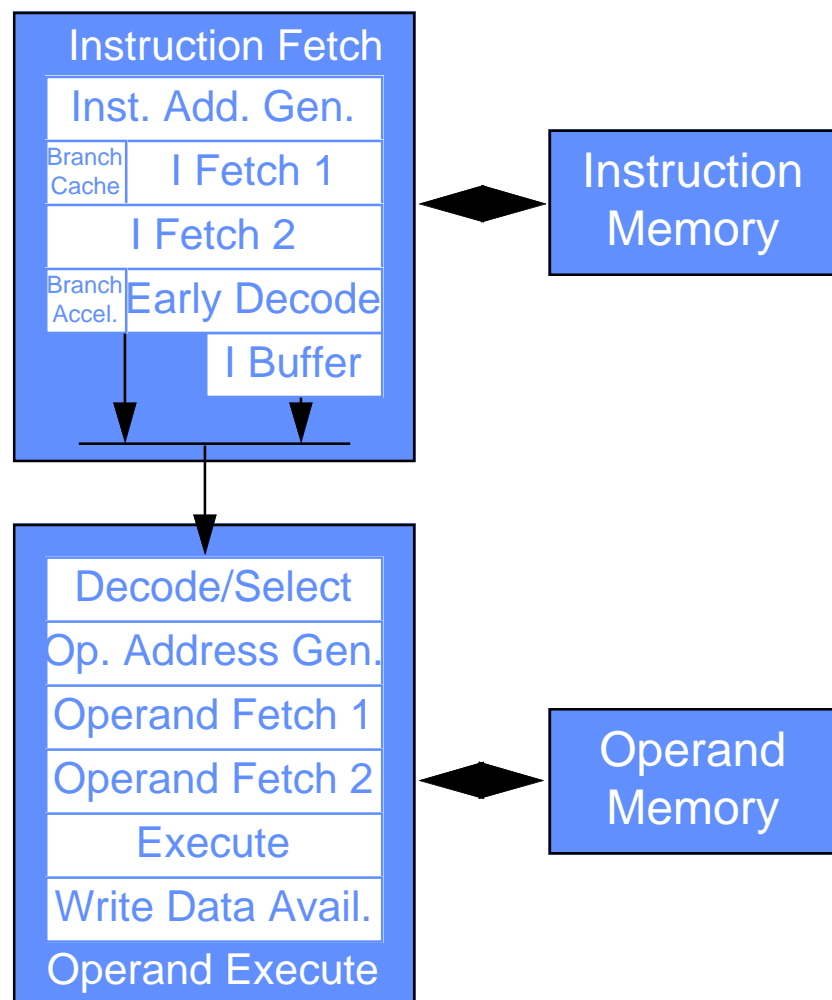
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Version 4 **ColdFire®** Core



- Independent, decoupled pipelines
 - 4-stage Instruction Fetch Pipeline (IFP)
 - 5-stage Operand Execution Pipeline
 - FIFO I-Buffer is the decoupling mechanism
- Limited superscalar execution through use of instruction folding
 - Approaches dual-issue performance but at a much lower silicon cost
- Harvard memory architecture
- Most instructions execute in 1 cycle
- Sophisticated 2-level branch acceleration mechanisms in the IFP minimize execution time of change-of-flow instructions

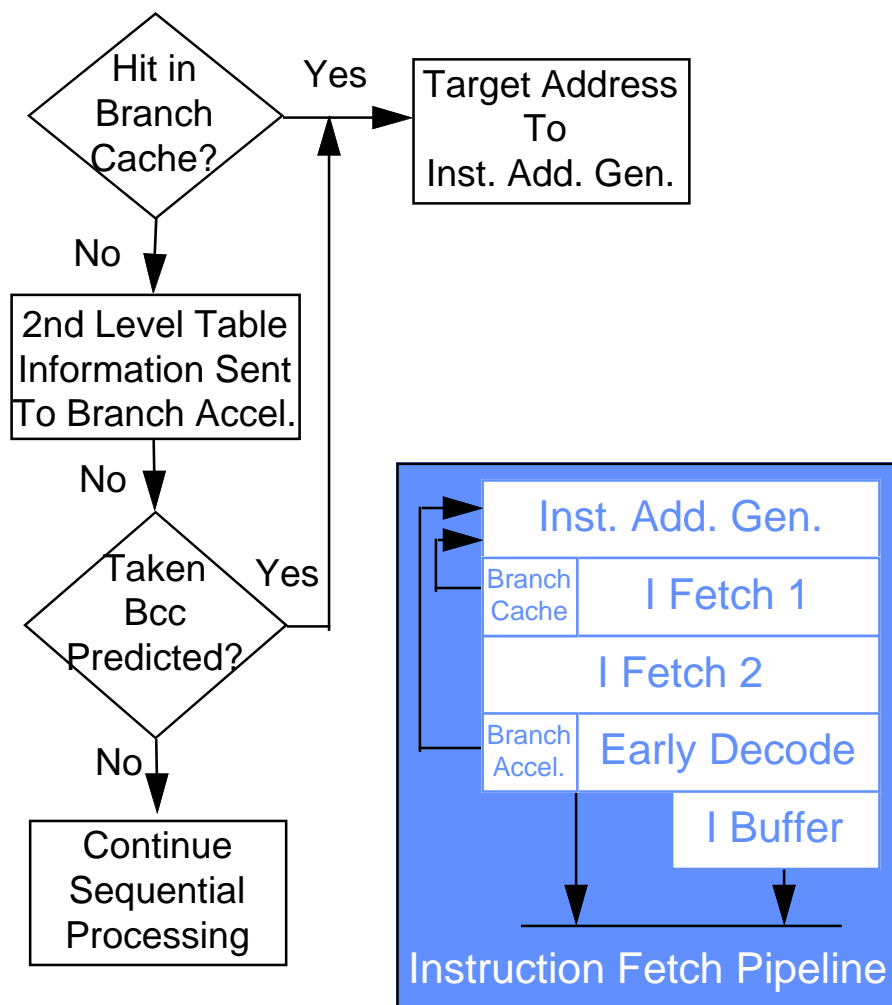


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V4 Branch Execution

- Two-level hierarchical scheme:
 - 8-entry, direct-mapped branch cache
 - 128-entry, direct-mapped table
- 2-bit prediction per entry
- Instruction folding in branch cache on conditional branches for zero-cycle execution
- Unconditional branch calculates target address in Early Decode stage and sends to Inst. Addr. Gen. stage
- 4-entry LIFO hardware stack in Early Decode stage to accelerate subroutine return instructions



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V4 Operand Execution Pipeline (OEP)

- Basic 5-stage execution pipeline
 - Built upon two 2-stage “compute engines”
 - 1st stage = Register File, 2nd stage = ALU
 - Implemented in 1st/2nd stages, 4th/5th stages
 - Optional 6th stage for instructions that store results in memory
- Optimized OAG compute engine
 - Normally used for operand address generation
 - Also used for instruction execution for certain opcodes
 - ISA broadly grouped into 3 categories
 - Always executed in EX (e.g., add.l <mem>,Rx)
 - Always executed in OAG (e.g., lea <ea>,Rx)
 - Can be executed in either (e.g., add.l Ry,Rx)
 - OEP always attempts to relocate execution to OAG engine
- OAG execution plus register renaming resources provides flexibility to minimize pipeline stalls and increase performance



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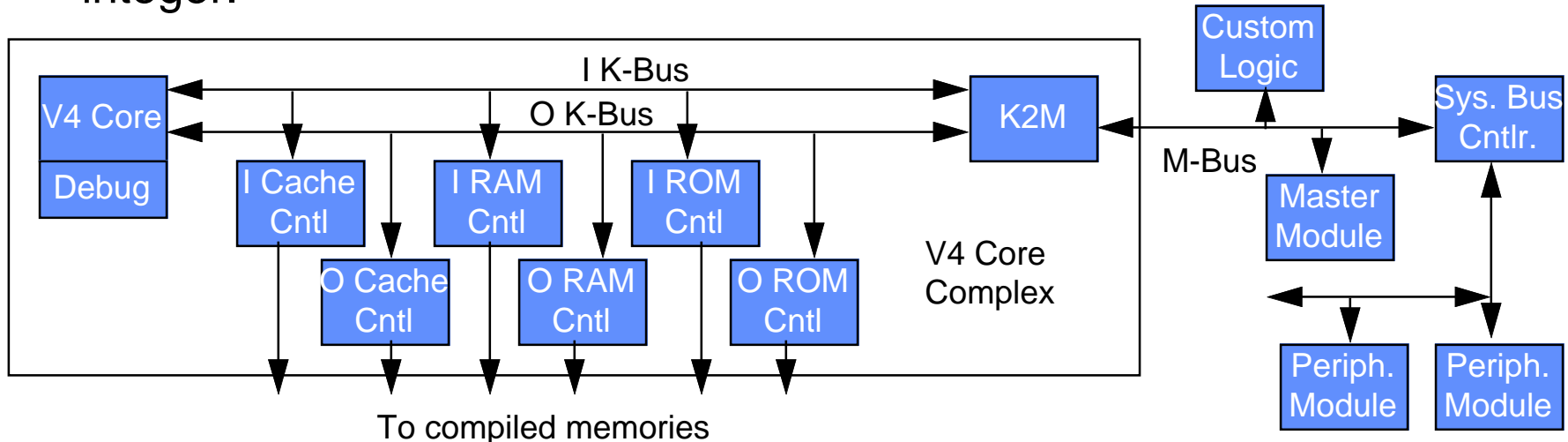
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V4 Memory Structure

- V4 Operand Execution Pipeline requires higher KBus bandwidth than previous generations plus operates at higher frequencies.
- Harvard bus architecture doubles available KBus bandwidth, removes instruction and operand conflicts, and provides more flexibility for local memory configurations.
- Design supports multiple clock domains, where core complex operates at n:1 speed compared to the M-Bus speed where n is any integer.



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Predicted Version 4 Performance

- V4 predicted performance analysis
 - Use of architectural models similar to those used in V2, V3 analysis work
 - Large set of embedded applications and benchmarks
 - Configurations
 - Version 4
150/75 MHz, 8 KByte I- & O-Caches, 6-3-3-3 (70 ns DRAM) external memory system
 - Version 3
90/45 MHz, 8 KByte U-Cache, 4-2-2-2 (70 ns DRAM) external memory system
 - Copyback cache mode, no internal SRAM used, no MAC instructions, no new instructions included
 - V4 performance provided by a combination of factors:
 - 1.6x frequency factor
 - 1.3x - 1.5x architectural improvement factor
 - **150/75 MHz Version 4 = 2.1 - 2.5 x 90/45 MHz Version 3**
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ColdFire® ISA Additions

Added Instructions

Move 3-bit Data Quick
Move with Sign Extend
Move with Zero-Fill
Move Data Source to Destination, byte and word*
Compare, byte and word*
Compare Immediate, byte and word*
Branch Conditionally, 32-bit displacement*
Branch Always, 32-bit displacement*
Branch to Subroutine, 32-bit displacement*
Signed Saturate
Test and Set an Operand*

* Implementation of 68K opcodes

Functionality added based on input from tool developers and customers to:

- Enhance code density
- Improve performance
- Enhance support for byte, word size operands
- Enhance support for position-independent code
- Assist 68K assembly code migration to **ColdFire** code

By incorporating these ISA changes, the following architectural metrics were measured across a wide range of applications:

- **Static code size reduction up to 6%**
- **Dynamic pathlength reduction up to 12%**
- **Performance improvement up to 10%**



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ColdFire[®] MAC and Debug Additions

- Multiply-Accumulate Unit Enhancement
 - Addition of signed, fixed-point fractionals to extend the precision range
 - Provides better results for exacting applications (e.g., Digital Audio)
- Debug Enhancements for Rev C
 - Additional on-chip breakpoint registers
 - 3 more PC breakpoint registers
 - Another address range & Data+Mask
 - Ability to service I/O interrupts while in “emulator mode”
 - Functionality added based on input from tool developers and customers to enhance support for real-time debug
- As with all optional **ColdFire** modules, these modules are easily incorporated into any version of **ColdFire** core
 - For example, enhanced MAC unit will be included in next mask set of MCF5307

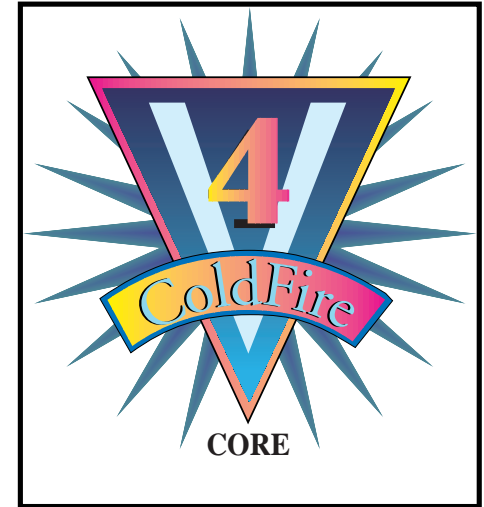


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Version 4 **ColdFire®** Core Summary

- Next-generation **ColdFire** microarchitecture provides a 2.5x performance improvement over current V3 designs
 - Improved microarchitecture for higher performance: greater than 200 Dhrystone 2.1 MIPS @ 150 MHz
 - Small set of new instructions for better code density and performance
 - Enhanced MAC and debug functionality
 - Core size = 4.5 mm² in 0.25 micron drawn process
 - Preliminary model already deployed to Hewlett-Packard's Integrated Circuit Business Division
 - Version 4 core design complete in November 1998
- First standard V4 integrated microprocessors available 2Q99
- Binary compatibility between 68K and **ColdFire** using software emulation
- Approaching \$3 Billion in committed design wins.....



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